


# MATERIAL DECLARATION SHEET



Material Number	<b>CRM2512-FT</b>			
Product Line	<b>Surface Mount Chip Resistor</b>			
Compliance Date	<b>2007-07-27</b>			
RoHS Compliant	<b>Yes</b>	MSL	<b>1</b>	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Body	Substrate	34.7438	aluminum oxide	1344-28-1	96	80.54	95.6893
				silicon dioxide	7631-86-9	2		
				magnesium oxide	1309-48-4	2		
		Top conductor	0.6157	silver	7440-22-4	100	2.06	
		Side conductor	0.8142	silver	7440-22-4	95	5.82	
				lead oxide	1317-36-8	3		
				chromium III	7440-47-3	2		
		Back conductor	0.3152	silver	7440-22-4	100	0.89	
		Resistor	0.3821	ruthenium dioxide	12036-10-1	30	1.17	
				silver	7440-22-4	20		
				silicon dioxide	7631-86-9	20		
				lead oxide	1317-36-8	8.861		
				palladium	7440-05-3	17		
				boron oxide	1303-86-2	4.139		
		First encapsulating	0.3685	lead oxide	1317-36-8	29.5	1.12	
				silicon dioxide	7631-86-9	60.5		
				boron oxide	1303-86-2	10		
Overcoat	0.8454	lead oxide	1317-36-8	29.5	2.30			
		silicon dioxide	7631-86-9	60.5				
		boron oxide	1303-86-2	10				
Marking	0.0525	lead oxide	1317-36-8	29.5	0.28			
		silicon dioxide	7631-86-9	60.5				
		boron oxide	1303-86-2	10				
2	Termination layer	Plating (Middle)	0.6872	nickel	7440-02-0	100	2.33	4.3110
		Plating (Outer)	1.0308	tin (matte)	7440-31-5	100	3.48	
			Total weight			39.8551		

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**This Document was updated on:**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption: 5 – lead in glass ... of electronic components.